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REES Workshop 2017

2nd International Workshop on Resiliency in Embedded Electronic Systems

March 31, 2017

SwissTech Convention Center, Lausanne, Switzerland

General Co-Chairs
Daniel Müller-Gritschneder, Technical University of Munich, Germany
Wolfgang Müller, Heinz Nixdorf Institute/University of Paderborn, Germany
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The REES workshop is a joint academic/industry forum considering multiple resiliency aspects from software to hardware and from embedded systems to chip level designs.

With the sheer complexity of hardware and software systems, resiliency became a major challenge in embedded systems design, manufacturing, and operation. For industrial applications several standards such as ISO26262, IEC61508 or DO-254 prescribe a well-defined level of reliability, robustness, and fault-tolerance.

This joint academic/industry workshop addresses all resiliency aspects in hardware and software systems design and operation from different embedded system areas such as automotive, avionics, and industry automation. This includes, but is not limited to, design bugs and cross-layer and cross-domain design techniques from software (applications, operating systems, middleware) to hardware (system, architecture, circuits, device level). Of special interest are design-for-resiliency technologies, resilient-specific design flows, like integrated functional/stochastic approaches, and development frameworks for robust designs, such as virtual prototyping approaches, which support early evaluations and estimations to obtain high reliability with less cost.

Program

REES 2017 features a range academic talks with poster presentations from internal research groups as well as exciting industrial presentations from **ARM Limited, NXP, Bosch GmbH, Hewlett Packard Enterprise, ST Microelectronics, Infineon Technologies,** and **Mentor Graphics**. The final program is now available at https://www.edacentrum.de/rees/program [1]

Proceedings (Current and past events)

- REES 2017 final proceedings available: Download REES 2017 final proceedings [8] .
- REES 2015 final proceedings available: Download REES 2015 final proceedings [9].

Organisation

Information on Technical comittee [10]. The workshop is supported by the DFG through the priority program Dependable Embedded Systems (SPP1500) [11] and the BMBF through the project EffektiV [12].

Quell-URL: https://www.edacentrum.de/rees

Links:
[1] https://www.edacentrum.de/rees/program
[2] https://www.date-conference.com/registration
[3] https://www.edacentrum.de/en/rees/invited-talks
[4] https://www.edacentrum.de/system/files/images/REES-Workshop/CFS-REES2017.pdf
[5] https://www.ieee.org/conferences_events/conferences/publishing/templates.html
[6] https://www.edacentrum.de/en/rees/upload
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[8] http://adt.cs.upb.de/REES2017-Proceedings.pdf
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[12] http://www.edacentrum.de/effektiv